

Aeroflex / Inmet and Richardson Sign Agreement

Aeroflex / Inmet announced that it has signed a distribution agreement with Richardson Electronics. Under the terms of the agreement, Richardson will operate as exclusive worldwide distributor of a selected and extensive range of Aeroflex / Inmet products including fixed attenuators, terminations, DC blocks, Bias Tees, and adapters.

CSR's BlueCore used by Agere

CSR (LSE: CSR.L) today announced that BlueCore has been selected by Agere Systems for its latest EDGE/GPRS reference platform for feature rich multimedia mobile phones. CSR's BlueCore will provide the Bluetooth wireless connectivity to the Agere handset design, which offers time-to-market savings of up to 3 months.

Qualcomm and Siemens Announce Partnership

Qualcomm and Siemens announced a strategic relationship to use QUALCOMM chipsets in upcoming WCDMA-based multimedia handsets from Siemens. With WCDMA shown to exceed the performance of GSM/GPRS and with the technology now a reality worldwide, this announcement underscores the increased momentum in Europe and the United States to transition to 3G mobile services.

M/A-COM Signs Contract with Raytheon

M/A-COM announced that it has signed an initial development contract with Raytheon Missiles Systems for Tactical Telemetry Modules (TTM) for the XM982 "Excalibur" projectile program. The TTM will telemeter critical on-board sensor and system health information during the projectile's flight, and will be utilized throughout the life cycle of the projectile.

GENESYS Selected by Rohde & Schwarz

Eagleware Corporation announced that Rohde & Schwarz has chosen the GENESYS suite of enterprise-level tools for RF and microwave design to increase productivity and enhance co-ordination in their design teams. GENESYS enterprise-level tools enable engineers to share files, export and import files from other programs, and

easily create and access models and part libraries.

Wireless Telecom Group Acquires Willtek

Wireless Telecom Group, Inc. announced it entered into a definitive agreement to acquire all of the outstanding capital stock of privately held Willtek Communications GmbH. As a result of the proposed acquisition, Willtek will become a wholly-owned subsidiary of WTT.

WJ Reports Third Quarter Results

WJ Communications, Inc. announced results for its third quarter ended September 26th, 2004. These are the first full quarter combined results following WJ Communications' acquisition of the infrastructure business and associated assets of EiC Corporation effective June 18th, 2004. Revenue for the third quarter of 2004 was up 29% to \$8.9 million from \$6.9 million in the same period of 2003. Revenue from the Company's RF IC semiconductor business continued to expand, increasing 60% from the same period last year and 18% sequentially to \$8.4 million.

Modelithics and dBm Engineering Establish Strategic Alliance

Modelithics, Inc. and dBm Engineering, Inc. enter a strategic partnership to provide customers with combined services for measurement and modeling of high- power transistors. The strength of the combined offering will address the stringent demands of Power Amplifier (PA) designers for improved characterization data and models for high power, non-linear designs and simulations. The cumulative resources and expertise of the two companies will provide services ranging from wafer probe power levels to multi-hundred watt measurements on devices ranging from passive components to packaged high power discrete transistors to complete amplifier circuits.

National Semiconductor announces sale of Imaging business to Eastman Kodak

National Semiconductor Corporation announces that it has signed a definitive agreement to sell its Imaging business to Eastman Kodak Company. As part of this agreement, Kodak will acquire certain assets, including intellectual property and equipment, and plans to hire approximately 50 employees, currently supporting National's Imaging business.

Peregrine Semiconductor Unveils Process for High-Performance RF and Mixed-Signal IC Manufacturing

Peregrine Semiconductor Corporation announces that its 0.25µm UltraCMOS¹⁵³ Silicon-on-Sapphire process technology is available for foundry services. Two processes, designated as GA and GC, complement the existing 0.50µm FA and FC processes and will push the transistor performance beyond the 100 GHz F(max) mark.

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